

Application No. 10/677,292
Response to Office Action

Patent
Attorney docket No. 86654-4
(formerly 86177-79)

II. AMENDMENTS TO THE CLAIMS

Please find below a complete listing of the claims in the application, including their status as effected by the present amendment:

1. (cancelled)
2. (currently amended) A method ~~[[as defined in claim 1, wherein the]]~~
for cooling a microelectronic complex [[is]] including a plurality of
discrete functional modules formed on a unitary body of semiconductor
material, said method comprising:
 - a) during operation of the microelectronic complex, dynamically
assessing a cooling requirement of each discrete functional
module of the microelectronic complex formed on the unitary
body of semiconductor material;
 - b) cooling the discrete functional modules independently from one
another on the basis of the cooling requirements assessed at
step a).
3. (currently amended) A method as defined in claim 2, wherein in
operation the microelectronic complex utilizes signals associated with
respective ones of said plurality of discrete functional modules, each
signal containing information allowing to determine the cooling
requirement of the respective discrete functional module, said method
including:
 - c) computing an amount of cooling required by a particular discrete
functional module on the basis of the signal associated with the
particular discrete functional module;
 - d) cooling the particular discrete functional module on the basis of the
amount of cooling computed at step c) ~~[[a]]~~.

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4. (original) A method as defined in claim 3, wherein computing an amount of cooling required by a particular discrete functional module includes determining an amount of heat generated by the particular discrete functional module.
5. (original) A method as defined in claim 4, wherein said signals are electric signals.
6. (original) A method as defined in claim 5, wherein said signals are voltage signals.
7. (original) A method as defined in claim 5, wherein said signals are current signals.
8. (original) A method as defined in claim 4, wherein said signals are optical signals.
9. (original) A method as defined in claim 3, wherein computing the amount of cooling required by a particular discrete functional module includes determining a temperature of the particular discrete functional module.
10. (original) A method as defined in claim 2, wherein assessing the cooling requirement of a particular discrete functional module includes monitoring a temperature differential between the particular discrete functional module and at least one other discrete functional module of said plurality of discrete functional modules.
11. (original) A method as defined in claim 10, wherein monitoring the temperature differential between the particular discrete functional module and at least one other discrete functional module includes

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tracking the temperature of the at least one other discrete functional module.

12. (original) A method as defined in claim 11, wherein cooling a particular discrete functional module includes adjusting the temperature of the particular discrete functional module to substantially match the tracked temperature of the at least one other discrete functional module.
13. (original) A method as defined in claim 10, wherein the at least one other discrete functional module is adjacent the particular discrete functional module on said body of unitary semiconductor material.
14. (original) A method as defined in claim 2, wherein assessing the cooling requirement of a particular discrete functional module includes monitoring a differential between an amount of heat generated by the particular discrete functional module and an amount of heat generated by at least one other discrete functional module of said plurality of discrete functional modules.
15. (original) A method as defined in claim 14, wherein the differential between the amount of heat generated by the particular discrete functional module and the amount of heat generated by the at least one other discrete functional module of said plurality of discrete functional modules is assessed using a measurement of a differential between a current entering the particular discrete functional module and a current entering the at least one other discrete functional module.
16. (original) A method as defined in claim 15, wherein the differential between the current entering the particular discrete functional module and the current entering the at least one other discrete functional

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module is assessed using a differential current measurement sensor connected between the particular discrete functional module and the at least one other discrete functional module.

17. (original) A method as defined in claim 2, wherein cooling the discrete functional modules independently from one another includes the step of independently controlling cooling modules in a thermal exchange relationship with respective ones of the plurality of discrete functional modules.
18. (cancelled)
19. (currently amended) A cooling device ~~[[as defined in claim 18,]]~~ for a microelectronic complex including a plurality of discrete functional modules, said cooling device comprising:
 - a) a plurality of independent cooling modules, each cooling module being adapted to establish a thermal exchange relationship with a respective one of the plurality of discrete functional modules;
 - b) control logic for dynamically assessing a cooling requirement of each discrete functional module during operation of the microelectronic complex, said control logic operative to adjust an amount of cooling provided by each cooling module to the respective discrete functional module on a basis of the assessed cooling requirement of the respective discrete functional modulewherein each cooling module is operable ~~[[capable to operate]]~~ within a range of cooling levels, from a predetermined minimum cooling level to a predetermined maximum cooling level, said control logic being operative to dynamically adjust the cooling level of a particular cooling module on the basis of the assessed cooling requirement of the respective discrete functional module.

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20. (currently amended) A cooling device as defined in claim 19 ~~[[18]]~~, wherein the assessment includes the determination of an amount of cooling required by each discrete functional module.
21. (currently amended) A cooling device as defined in claim 19 ~~[[18]]~~, wherein said control logic is distributed among the plurality of cooling modules, whereby each cooling module includes local control logic.
22. (currently amended) A cooling device as defined in claim 19 ~~[[18]]~~, wherein said control logic is distributed among the plurality of discrete functional modules, whereby each discrete functional module includes local control logic.
23. (currently amended) A cooling device ~~[[as defined in claim 18,]]~~ for a microelectronic complex including a plurality of discrete functional modules, said cooling device comprising:
- a) a plurality of independent cooling modules, each cooling module being adapted to establish a thermal exchange relationship with a respective one of the plurality of discrete functional modules;
 - b) control logic for dynamically assessing a cooling requirement of each discrete functional module during operation of the microelectronic complex, said control logic operative to adjust an amount of cooling provided by each cooling module to the respective discrete functional module on a basis of the assessed cooling requirement of the respective discrete functional module
- wherein said control logic is centralized for the plurality of cooling modules, whereby said cooling device includes a single control logic unit for controlling the operation of said plurality of independent cooling modules.

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24. (currently amended) A cooling device ~~[[as defined in claim 18,]]~~ for a microelectronic complex including a plurality of discrete functional modules, said cooling device comprising:
- a) a plurality of independent cooling modules, each cooling module being adapted to establish a thermal exchange relationship with a respective one of the plurality of discrete functional modules, [[wherein]] each cooling module [[is]] being a thermo-electric cooler;
 - b) control logic for dynamically assessing a cooling requirement of each discrete functional module during operation of the microelectronic complex, said control logic operative to adjust an amount of cooling provided by each cooling module to the respective discrete functional module on a basis of the assessed cooling requirement of the respective discrete functional module.
25. (currently amended) A cooling device ~~[[as defined in claim 18,]]~~ for a microelectronic complex including a plurality of discrete functional modules, said cooling device comprising:
- a) a plurality of independent cooling modules, each cooling module being adapted to establish a thermal exchange relationship with a respective one of the plurality of discrete functional modules, [[wherein]] each cooling module [[is]] being a thermo-electric cooler;
 - b) control logic for dynamically assessing a cooling requirement of each discrete functional module during operation of the microelectronic complex, said control logic operative to adjust an amount of cooling provided by each cooling module to the respective discrete functional module on a basis of the assessed cooling requirement of the respective discrete functional module;

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c) [[comprising]] a plurality of current differential measurement

sensors connected between adjacent discrete functional modules
for assessing a current differential between the adjacent
discrete functional modules.

26. (cancelled)

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